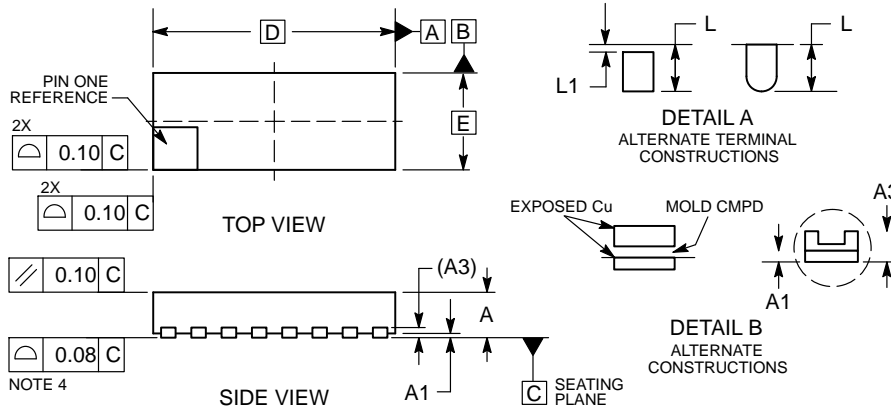


WDFN16, 4x1.6, 0.5P
CASE 511AU i01
ISSUE O

16

DATE 06 JUL 2010

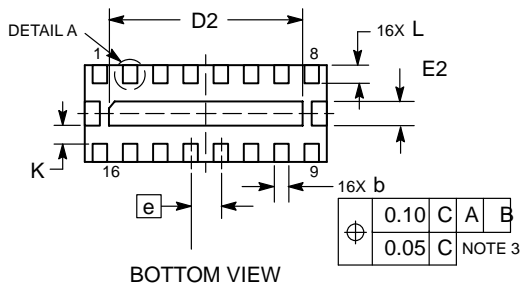
1
SCALE 4:1



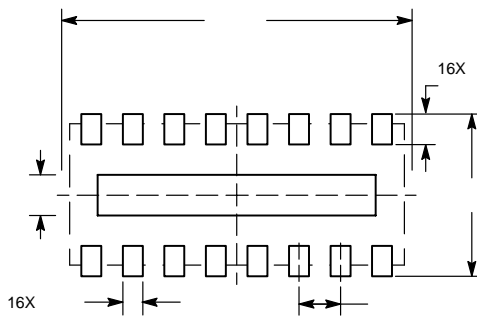
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	4.00 BSC	
D2	3.10	3.30
E	1.60 BSC	
E2	0.30	0.50
e	0.50 BSC	

L	0.20	0.40
L1	iii	0.15



RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.